



MATERIAL DECLARATION DATA SHEET

Device Name	Package Type	Pkg Wt (g)			
M2GL060	VFG784(23x23mm)	2.39			
Material Breakdown of Component	Material Breakdown (%)	Substance Name	CAS No.	Weight (g)	Substance Mass (%)
MOLD COMPOUND	40.08	Silica	60676-86-0	0.8879	92.7
		Resin	Proprietary	0.0479	5
		Metal Hydroxide	Proprietary	0.0192	2
		Carbon Black	1333-86-4	0.0029	0.3
				0.95786	100
SUBSTRATE	34.60	Bismaleimide/Triazine	13676-54-5	0.5429	65.65
		Copper (Cu)	7440-50-8	0.2642	31.95
		Gold (Au)	7440-57-5	0.0032	0.385
		Nickel (Ni)	7440-02-0	0.0167	2.015
				0.8270	100
DIE	2.09	Silicon	7440-21-3	0.0500	100
				0.0500	100
DIE ATTACH EPOXY	0.32	Silver	7440-22-4	0.0057	76
		Epoxy Resin	Proprietary	0.0018	24
				0.0076	100
SOLDER BALL	21.43	Tin	7440-31-5	0.4942	96.5
		Silver	7440-22-4	0.0154	3
		Copper (Cu)	7440-50-8	0.0026	0.5
				0.5121	100
GOLD WIRE	1.49	Gold	7440-57-5	0.0355	99.99
		Doping	Proprietary	0.0000	0.01
				0.0355	100
				2.3900	

Disclaimer: Microsemi believes this information to be correct, but cannot guarantee its completeness or accuracy. The information is based on data received from sources outside our company.

Revision No.	Date	Description of Change
	10/18/2022	Original release